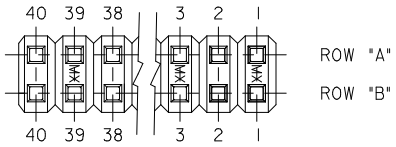
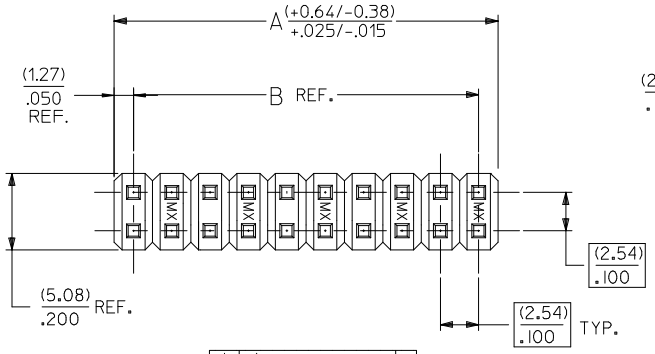
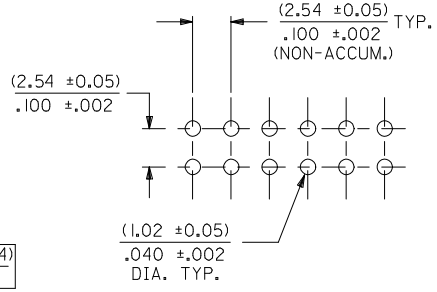
CKT. SIZE	DIM. A REF. (MM)	DIM. A REF. INCH	DIM. B REF. (MM)	DIM. B REF. INCH
4	(5.08)	.200	(2.54)	.100
6	(7.62)	.300	(5.08)	.200
8	(10.16)	.400	(7.62)	.300
10	(12.70)	.500	(10.16)	.400
12	(15.24)	.600	(12.70)	.500
14	(17.78)	.700	(15.24)	.600
16	(20.32)	.800	(17.78)	.700
18	(22.86)	.900	(20.32)	.800
20	(25.40)	1.000	(22.86)	.900
22	(27.94)	1.100	(25.40)	1.000
24	(30.48)	1.200	(27.94)	1.100
26	(33.02)	1.300	(30.48)	1.200
28	(35.56)	1.400	(33.02)	1.300
30	(38.10)	1.500	(35.56)	1.400
32	(40.64)	1.600	(38.10)	1.500
34	(43.18)	1.700	(40.64)	1.600
36	(45.72)	1.800	(43.18)	1.700
38	(48.26)	1.900	(45.72)	1.800
40	(50.80)	2.000	(48.26)	1.900
42	(53.34)	2.100	(50.80)	2.000
44	(55.88)	2.200	(53.34)	2.100
46	(58.42)	2.300	(55.88)	2.200
48	(60.96)	2.400	(58.42)	2.300
50	(63.50)	2.500	(60.96)	2.400
52	(66.04)	2.600	(63.50)	2.500
54	(68.58)	2.700	(66.04)	2.600
56	(71.12)	2.800	(68.58)	2.700
58	(73.66)	2.900	(71.12)	2.800
60	(76.20)	3.000	(73.66)	2.900
62	(78.74)	3.100	(76.20)	3.000
64	(81.28)	3.200	(78.74)	3.100
66	(83.82)	3.300	(81.28)	3.200
68	(86.36)	3.400	(83.82)	3.300
70	(88.90)	3.500	(86.36)	3.400
72	(91.44)	3.600	(88.90)	3.500
74	(93.98)	3.700	(91.44)	3.600
76	(96.52)	3.800	(93.98)	3.700
78	(99.06)	3.900	(96.52)	3.800
80	(101.60)	4.000	(99.06)	3.900
82	(104.14)	4.100	(101.60)	4.000
84	(106.68)	4.200	(104.14)	4.100
86	(109.22)	4.300	(106.68)	4.200
88	(111.76)	4.400	(109.22)	4.300
90	(114.30)	4.500	(111.76)	4.400
92	(116.84)	4.600	(114.30)	4.500
94	(119.38)	4.700	(116.84)	4.600
96	(121.92)	4.800	(119.38)	4.700
98	(124.46)	4.900	(121.92)	4.800
100	(127.00)	5.000	(124.46)	4.900



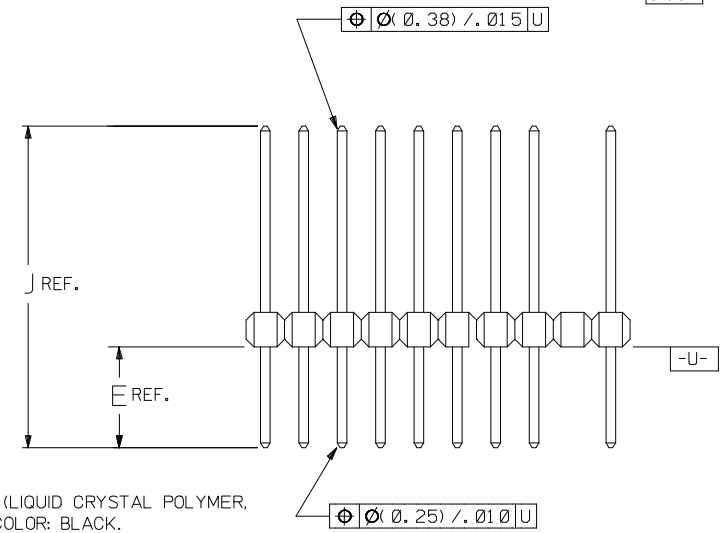
VIEW "AB"

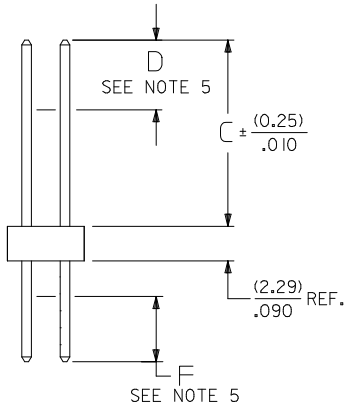
USE FOR LOCATING VOIDED CKTS.
(TOP VIEW SHOWN)
(SEE NOTE 6)





RECOMMENDED P.C. BOARD HOLE LAYOUT





NOTES:

1. MATERIAL:
   PIN: COPPER ALLOY
   WAFER: GLASS FILLED LCP (LIQUID CRYSTAL POLYMER, UL 94V-0, COLOR: BLACK.
2. FINISH:
   TIN = (0.00380)/.000150 MINIMUM TIN PLATE OVER (0.00127)/.000050 MINIMUM NICKEL PLATE.
   15 GOLD = (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA, (0.00190)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER (0.00127)/.000050 MINIMUM NICKEL PLATE OVERALL.
   30 GOLD = (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA, (0.00190)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER (0.00127)/.000050 MINIMUM NICKEL PLATE OVERALL.
   15G/100T = (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA, (0.00254)/.000100 MINIMUM TIN PLATE IN SELECT AREA, OVER (0.00127)/.000050 MINIMUM NICKEL PLATE OVERALL.

* THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD PLATING.

3. PRODUCT SPECIFICATION: PS-70280
4. PACKAGING INFORMATION: (UNLESS OTHERWISE NOTED IN TABLES) BULK PACK PER PK-70873-0353.
5. MEASURE POINT FOR PLATING THICKNESS.
6. VOIDED PIN LOCATIONS ARE IDENTIFIED NUMERICALLY FROM RIGHT TO LEFT AND ALPHABETICALLY FROM TOP TO BOTTOM USING VIEW "AB"; SEE CHART FOR LOCATION.
7. PIN PUSHOUT FORCE: 3 POUNDS MINIMUM IN EITHER DIRECTION.
8. FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
9. PINS MEET SOLDERABILITY SPEC SMES-152.
10. WAFER TO BE FLAT WITHIN (0.03 MM/CM) .003 IN./IN.
11. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

2	J1
1	K
SHT	REV

CORRECTED DIMENSION
EC NO: UCP2009-2631 2009/06/04
DRWN:TRBENES 2009/06/10
CHKD:MKIPPER 2009/06/12
APPR:FSMITH
DESCRIPTION
K
REV

QUALITY SYMBOLS
▼=0
▽(C)=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .005
2 PLACES	± 0.13	± .01
1 PLACE	± 0.25	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: RB DATE: 93/01/08
CHECKED BY: DATE:
APPROVED BY: DJB DATE: 93/01/08

TITLE: WAFER ASSY -HIGH TEMP DUAL ROW W/BREAK-OFF OPTION W/VOIDS

molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SDA-70280-5001-9999
SHEET NO.: 1 OF 2
SIZE: C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

OBSOLETE	ENGINEERING NUMBER	EDP NUMBER		CKT. SIZE	VOIDED PIN LOCATION (SEE NOTE 6) ROW	VOIDED PIN LOCATION (SEE NOTE 6) LOCATION	E REF.		J REF.	C ±.010 (0.25)	PLATING TYPE SEE SHEET 1	CONNECTOR END PLATING TYPE	CONNECTOR END PLATING D MEAS.		P.C. BOARD END PLATING TYPE	P.C. BOARD END PLATING F MEAS.		FOR PACKAGING INFORMATION, SEE NOTE #4 ON SHEET 1 (UNLESS OTHERWISE SPECIFIED BELOW)
	A-70280-5001	10-98-0004		26	B	1	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5002	10-98-0014		16	A	2	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5003	70280-5003		38	B	13	.125 (3.18)		.455 (11.56)	.240 (6.10)	15G/100T	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5004	70280-5004		08	B	2	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5005	70280-5005		06	A B	2 3	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5006	70280-500		20	A B	7 5	.107 (2.72)		.437 (11.10)	.240 (6.10)	TIN	TIN	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5007	70280-5007		10	A	1	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5008	70280-5008		16	A	7	.107 (2.72)		.437 (11.10)	.240 (6.10)	TIN	TIN	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5009	70280-5009		50	A	13	.107 (2.72)		.437 (11.10)	.240 (6.10)	TIN	TIN	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5010	70280-5010		26	B	1	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
X	A-70280-5011	70280-5011		26	A B	5,15,21 6,10,22	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5012	70280-5012		04	B	1,2	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5013	70280-5013		40	A	11	.107 (2.72)		.437 (11.10)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5014	70280-5014		10	A	5	.135 (3.43)		.465 (11.81)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5015	70280-5015		10	A	5	.135 (3.43)		.465 (11.81)	.240 (6.10)	30 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5016	70280-5016		10	A	5	.110 (2.79)		.440 (11.18)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5017	70280-5017		10	B	4	.110 (2.79)		.440 (11.18)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		
	A-70280-5018	70280-5018		16	A	3	.110 (2.79)		.440 (11.18)	.240 (6.10)	15 GOLD	GOLD	.100 (2.54)		TIN	.050 (1.27)		

UPDATE DIMENSIONS
EC NO: UCP2007-3272 2007/06/27
DRWN:ADERR 2007/06/27
CHKD:JBELL 2007/06/28
APPR:FSMITH
REV J1 DESCRIPTION

QUALITY SYMBOLS
▼=0
(C)=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: ---
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: RB DATE: 93/01/08
CHECKED BY: DATE:
APPROVED BY: DJB DATE: 93/01/08

TITLE: WAFER ASSEM.-HIGH TEMP. DUAL ROW W/BREAK-OFF OPTION W/VOIDS

molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SDA-70280-5001-9999
SHEET NO.: 2 OF 2
SIZE: C

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